




Laser Mark Guideline

07/29/2020

The purpose of this document is to provide an overview of actual mark layouts and product images.

XCB	<p>Product MPN starting with XCB prefix indicates Components are still attached to module. 75% effective yield.</p> <p>COB (Chip on Board) marked as marked for production. Mark Layout: 3 Lines</p>	
XCBB	<p>Product MPN starting with XCBB prefix indicates Components are still attached to module and have been blown and reconfigured. 75% effective yield.</p> <p>COB (Chip on Board) mark as marked for production. Mark Layout: Diamonds</p>	
PRN	<p>Product MPNs starting with a PRN prefix indicate Fully Tested Speed Graded 8 chip UDIMM only. 100% effective yield. (PRN components have SpecTek logo with no Micron logo).</p> <p>SpecTek standard mark as marked for production.</p>	
PRM	<p>Product MPNs starting with PRM prefix indicate Fully Tested Speed Graded 8 chip UDIMM only. 100% effective yield. (PRM components have original Micron mark with SpecTek logo over the top of Micron logo).</p> <p>SpecTek standard mark as marked for production.</p>	
TP	<p>Product MPN ending with TP grade indicates 8 chip modules/MID. 95% effective yield.</p> <p>SpecTek standard mark as marked for production.</p>	
PG	<p>Untested Partial Good Mixed Bin with a variety of mixed defects including, but not limited to high ICC, missing balls, package issue, visual defects. 50% Effective Yield.</p> <p>Mark as marked for production. Mark Layout: 3 Lines</p>	

